

Date: - 3 Jul, 2006

Data Sheet Issue: - 2

Provisional Data

Wespack Phase Control Thyristor Types N1263JK160 to N1263JK180

Development Type No.: NX/159JK160-180

Absolute Maximum Ratings

	VOLTAGE RATINGS		MAXIMUM LIMITS	UNITS
V_{DRM}	Repetitive peak off-state voltage, (note 1)		1600-1800	V
V_{DSM}	Non-repetitive peak off-state voltage, (note 1)	_	1600-1800	V
V_{RRM}	Repetitive peak reverse voltage, (note 1)		1600-1800	V
V_{RSM}	Non-repetitive peak reverse voltage, (note 1)		1700-1900	V

	OTHER RATINGS		MAXIMUM LIMITS	UNITS
$I_{T(AV)M}$	Maximum average on-state current, T _{sin} =55°C, (n	1263	Α	
$I_{T(AV)M}$	Maximum average on-state current. T _{sink} =85°C, (r	ote 2)	860	Α
$I_{T(AV)M}$	Maximum average on-state current. T _{sink} =85°C, (F	ote 3)	453	Α
I _{T(RMS)M}	Nominal RMS on-state current, T _{sink} =25°C, (note 2	2)	2504	Α
I _{T(d.c.)}	D.C. on-state current, T _{sink} =25°C, (note 4)	/	2145	Α
I _{TSM}	Peak non-repetitive surge tp=10ms, Vm=60%VRRM	, (note 5)	15.0	kA
I _{TSM2}	Peak non-repetitive surge t _p =10ms, V _{rm} ≤10V, (not	16.5	kA	
I ² t	I^2 t capacity for fusing $t_p = 10$ ms, $\sqrt{m} = 60\%$ \sqrt{RRM} , (no	1.13×10 ⁶	A^2s	
l ² t	I^2 t capacity for fusing $t_p = 10 \text{ ms}, V_{rm} \le 10 \text{ V}, \text{ (note 5)}$		1.36×10 ⁶	A ² s
		(continuous, 50Hz)	100	
(di/dt) _{cr}	Critical rate of rise of on-state current (note 6)	(repetitive, 50Hz, 60s)	200	A/µs
		(non-repetitive)	400	
V_{RGM}	Peak reverse gate voltage		5	V
P _{G(AV)}	Mean forward gate power	4	W	
P_{GM}	Peak forward gate power	30	W	
T _{j op}	Operating temperature range	-40 to +125	°C	
T_{stg}	Storage temperature range		-40 to +150	°C

Notes

- 1) De-rating factor of 0.13% per °C is applicable for T_i below 25°C.
- 2) Double side cooled, single phase; 50Hz, 180° half-sinewave.
- Cathode side cooled, single phase; 50Hz, 180° half-sinewave.
- 4) Double side cooled.
- 5) Half-sinewave, 125°C T_j initial.
- 6) $V_D=67\%$ V_{DRM} , $I_{TM}=2000A$, $I_{FG}=2A$, $t_r \le 0.5 \mu s$, $T_{case}=125^{\circ}C$.



Characteristics

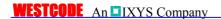
	PARAMETER	MIN.	TYP.	MAX.	TEST CONDITIONS (Note 1)	UNITS
V_{TM}	Maximum peak on-state voltage	-	-	1.59	I _{TM} =1700A	V
V_{TM}	Maximum peak on-state voltage	-	_	2.25	I _{TM} =3700A	V
V_{T0}	Threshold voltage	-	_	1.015		V
r _T	Slope resistance	-	_	0.332		mΩ
(dv/dt) _{cr}	Critical rate of rise of off-state voltage	1000	-	-	V _D =80% V _{DRM} , linear ramp, gate o/c	V/μs
I _{DRM}	Peak off-state current	-	_	100	Rated V _{DRM}	mA
I _{RRM}	Peak reverse current	-	-	100/	Rated V _{RRM}	mA
V_{GT}	Gate trigger voltage	-	-	3.0	T-25°C	V
I_{GT}	Gate trigger current	-	_	300 <	$T_j=25^{\circ}C$ $V_D=10V$, $I_T=3A$	mA
V_{GD}	Gate non-trigger voltage	-	-	0.25	Rated V _{DRM}	V
I _H	Holding current	-	-	1000	Tj=25°C	mA
t _{gd}	Gate-controlled turn-on delay time	-	0.5	1.5	V _D =67% V _{DRM} , I _T =1000A, di/dt=10A/μs,	μs
t_{gt}	Turn-on time	-	1.0	_2.0	I_{FG} =2A, t_r =0.5 μ s, T_j =25°C	μs
Q _{rr}	Recovered charge	-	1700	$\overline{}$	^	μC
Q _{ra}	Recovered charge, 50% Chord	-	1050	1/35/0	√ √ _{TM} =1000A, t _p =1000μs, di/dt=10A/μs,	μC
I _{rr}	Reverse recovery current	-	100		V _r =50∨	Α
t _{rr}	Reverse recovery time, 50% Chord	- /	2/			μs
t _q	Turn-off time	-(150 °	<u> </u>	I_{TM} =1000A, t_p =1000 μ s, di/dt =10A/ μ s, V_r =50V, V_{dr} =80% V_{DRM} , dV_{dr}/dt =20V/ μ s	μs
				0.0270	V _r =50V, V _{dr} =80%V _{DRM} , dV _{dr} /dt=200V/μs Double side cooled	K/W
R_{thJK}	Thermal resistance, junction to heatsink			0.0270	Anode side cooled	K/W
I \thJK	Thermal resistance, junction to fleats/fik	\		0.0409	Cathode side cooled	K/W
F	Mounting force	10	-			
	Mounting force	10	125	20	Note 2.	kN
W_t	Weight	-	135	-		g

Notes:-

1) Unless otherwise indicated T_i=125°C.

2) For other clamp forces, please consult factory.





Notes on Ratings and Characteristics

1.0 Voltage Grade Table

Voltage Grade	$V_{ m DRM}V_{ m DSM}V_{ m RRM}$	V _{RSM} V		V _D /V _R DC V
16	1600	1700	7	1040
18	1800	1900	>	1150

2.0 Extension of Voltage Grades

This report is applicable to other voltage grades when supply has been agreed by/Sales/Production.

3.0 De-rating Factor

A blocking voltage de-rating factor of 0.13%/°C is applicable to this device for T below 25°C.

4.0 Repetitive dv/dt

Standard dv/dt is 1000V/µs.

5.0 Snubber Components

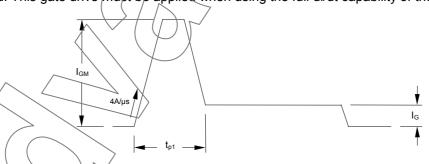
When selecting snubber components, care must be taken not to use excessively large values of snubber capacitor or excessively small values of snubber resistor. Such excessive component values may lead to device damage due to the large resultant values of snubber discharge current. If required, please consult the factory for assistance.

6.0 Rate of rise of on-state current

The maximum un-primed rate of rise of on-state current must not exceed 400A/µs at any time during turnon on a non-repetitive basis. For repetitive performance, the on-state rate of rise of current must not exceed 200A/µs at any time during turn-on. Note that these values of rate of rise of current apply to the total device current including that from any local snubber network.

7.0 Gate Drive

The nominal requirement for a typical gate drive is illustrated below. An open circuit voltage of at least 30V is assumed. This gate drive must be applied when using the full di/dt capability of the device.



The magnitude of I_{GM} should be between five and ten times I_{GT} , which is shown on page 2. Its duration (tpt) should be 20µs or sufficient to allow the anode current to reach ten times I_{L} , whichever is greater. Otherwise, an increase in pulse current could be needed to supply the necessary charge to trigger. The 'back-perch' current I_{G} should remain flowing for the same duration as the anode current and have a magnitude in the order of 1.5 times I_{GT} .

8.0 Computer Modelling Parameters

8.1 Device Dissipation Calculations

$$I_{AV} = \frac{-V_{T0} + \sqrt{{V_{T0}}^2 + 4 \cdot ff^2 \cdot r_T \cdot W_{AV}}}{2 \cdot ff^2 \cdot r_T}$$

$$W_{AV} = \frac{\Delta T}{R_{th}}$$

$$\Delta T = T_{j \text{ max}} - T_{K}$$

Where V_{T0} =1.015V, r_T =0.332m Ω ,

 R_{th} = Supplementary thermal impedance, see table below and

ff = Form factor, see table below.

			_/				
Supplementary Thermal Impedance							
Conduction Angle	30°	60°/	√90°	120°	\ 180°	270°	d.c.
Square wave Double Side Cooled	0.0369	0.0348	0.0329	0.0314	0.0299	0.0277	0.0270
Square wave Cathode Side Cooled	0.0740	0.0716	0.0695	0.0677	0.0667	0.0641	0.0636
Sine wave Double Side Cooled	0.0350	0.0330	0.0315	0.0300	0.0278		
Sine wave Cathode Side Cooled	0.0719	0.0696	0.0679	0.0668	0.0643		

Form Factors								
Conduction Angle	30°	60°	90°/) 1 <mark>20°</mark>	180°	270°	d.c.	
Square wave	3.46	2.45	7 2	1.73	1.41	1.15	1	
Sine wave	3.98	2.78	2/22	1.88	1.57			

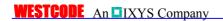
8.2 Calculating V_T using ABCD Coefficients

- The on-state characteristic I_T vs. V_T , on page 6 is represented in two ways; (i) the well established V_{T0} and r_T tangent used for rating purposes and (ii) a set of constants A, B, C, D, forming the coefficients of the representative equation for V_T in terms of I_T given below:

$$V_T = A + B \cdot \ln(I_T) + C \cdot I_T + D \cdot \sqrt{I_T}$$

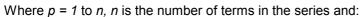
The constants, derived by curve fitting software, are given below for both hot and cold characteristics. The resulting values for V_T agree with the true device characteristic over a current range, which is limited to that plotted.

/					
\ >		25°C Coefficients	125°C Coefficients		
	A	1.125034479	Α	0.515189879	
	В	-0.03145424	В	0.06949785	
\	P	1.70934×10 ⁻⁴	С	2.83136×10 ⁻⁴	
	b	9.362494×10 ⁻³	D	1.856071×10 ⁻³	



8.3 D.C. Thermal Impedance Calculation

$$r_t = \sum_{p=1}^{p=n} r_p \cdot \left(1 - e^{\frac{-t}{\tau_p}}\right)$$



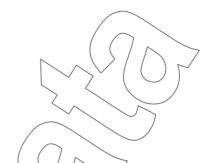
t = Duration of heating pulse in seconds.

 r_{t} = Thermal resistance at time t.

 r_p = Amplitude of p_{th} term.

 τ_p = Time Constant of r_{th} term.

The coefficients for this device are shown in the tables below:



D.C. Double Side Cooled							
Term	1	2	3	4			
r_p	0.01628776	5.61118×10 ⁻³	2.647435×10 ⁻³	2.309156×10 ⁻³			
$ au_{\!p}$	0.2858404	0.09388713	0.02816524	3.592634×10 ⁻³			

	D.C. Cathode Side Cooled							
Term	1	2	3	4				
r_p	0.04742413	0.01200315	2.629734×10 ⁻³	1.66852×10 ⁻³				
$ au_{p}$	1.793815	0.131/1505	0.01493408	2.829606×10 ⁻³				

9.0 Reverse recovery ratings

(i) Q_{ra} is based on 50% I_{rm} chord as shown in Fig. 1

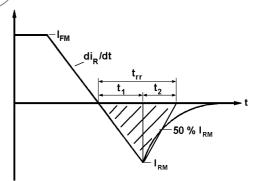
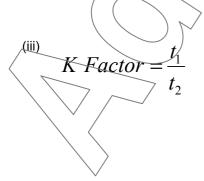


Fig. 1

(ii)
$$Q_{rr}$$
 is based on a 150 μ s integration time i.e.



$$Q_{rr} = \int_{0}^{150 \,\mu s} i_{rr}.dt$$

Curves

Figure 1 – On-state characteristics of Limit device

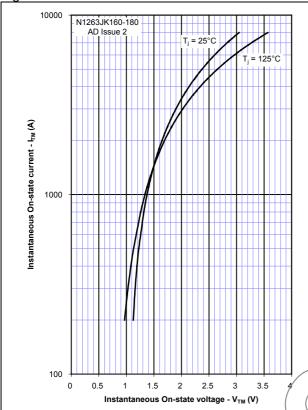
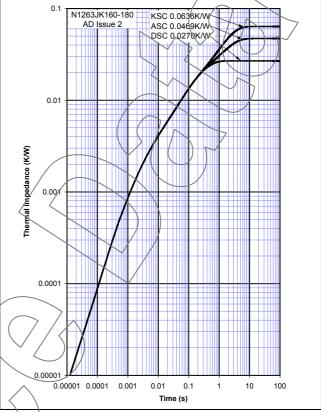


Figure 2 – Transient thermal impedance



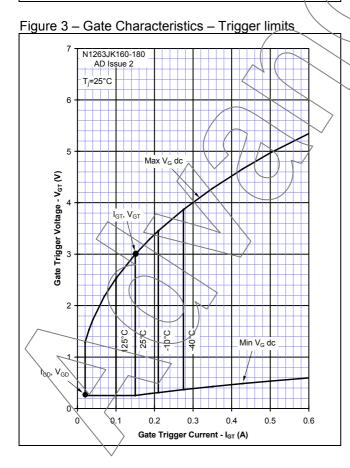
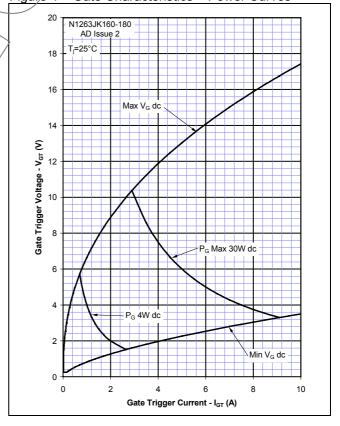
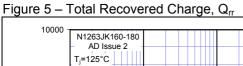


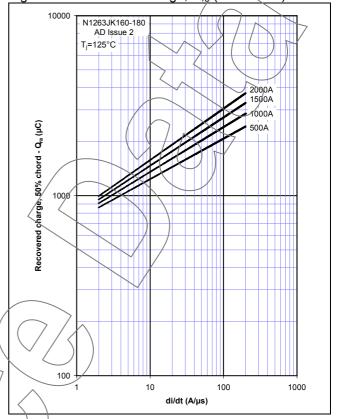
Figure 4 – Gate Characteristics – Power Curves





2000A 1500A 1000A 500A Recovered charge - Q_{rr} (µC) 1000 100 10 di/dt (A/µs)

Figure 6 – Recovered Charge, Q_{ra} (50% shord)



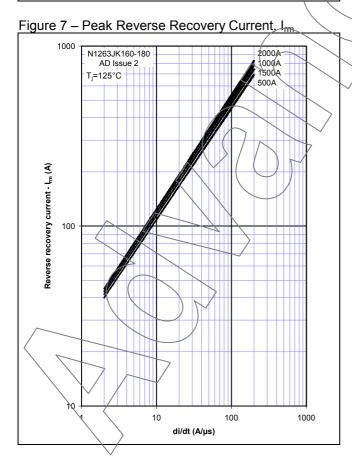


Figure 8 – Maximum Recovery Time, tr (50% chord)

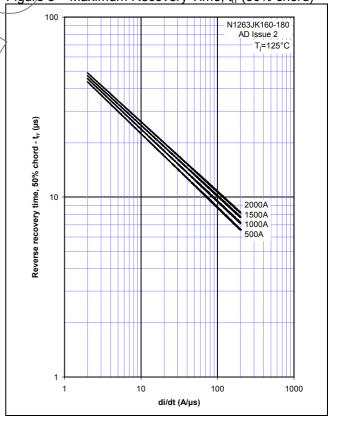


Figure 9 – On-state current vs. Power dissipation – Double Side Cooled (Sine wave)

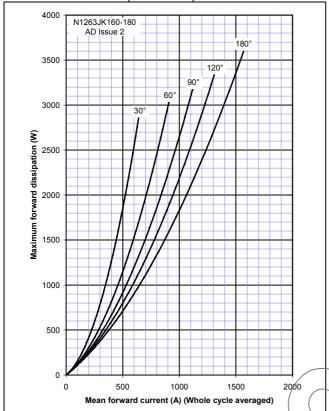


Figure 11 – On-state current vs. Power dissipation –

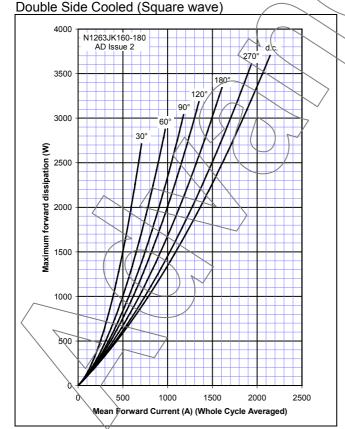
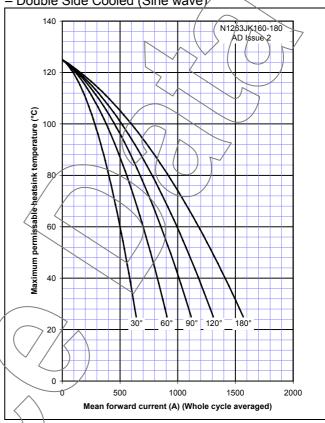


Figure 10 – On-state current vs. Heatsink temperature – Double Side Cooled (Sine wave)



Eigure 12 – On-state current vs. Heatsink temperature – Double Side Cooled (Square wave)

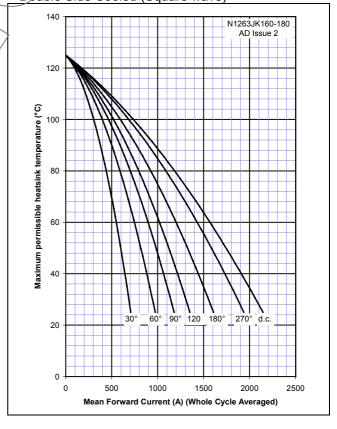


Figure 13 – On-state current vs. Power dissipation – Cathode Side Cooled (Sine wave)

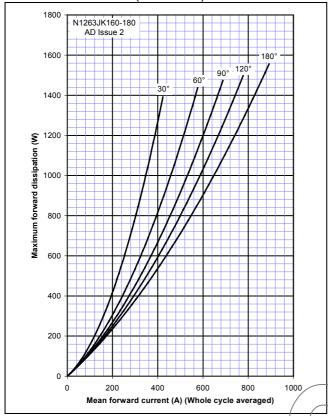


Figure 15 – On-state current vs. Power dissipation Cathode Side Cooled (Square wave)

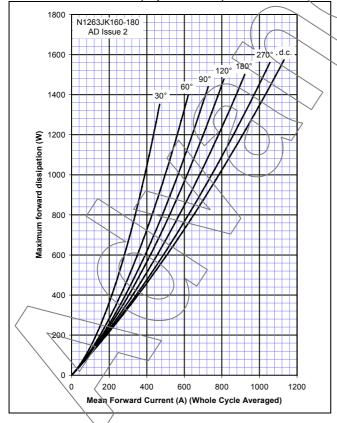


Figure 14 – On-state current vs. Heatsink temperature – Cathode Side Cooled (Sine wave)

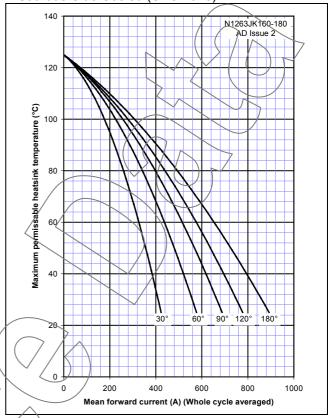
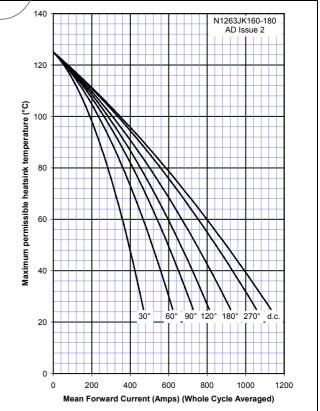
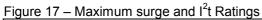
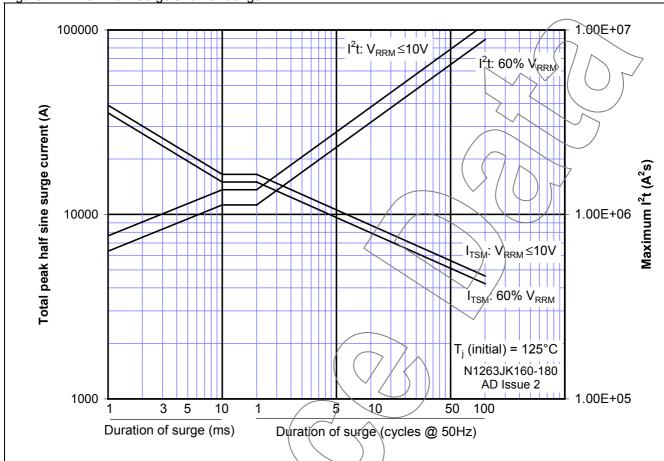


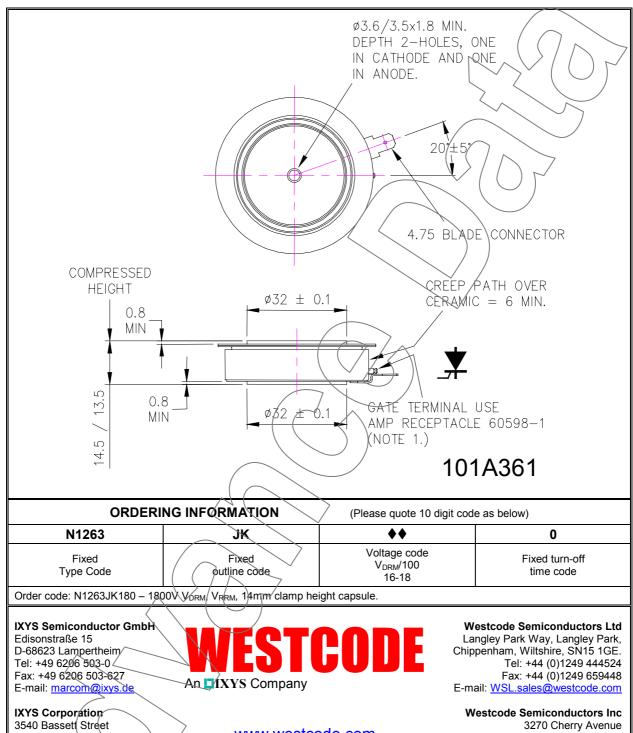
Figure 16 – On-state current vs. Heatsink temperature — Cathode Side Cooled (Square wave)







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